

UT7401

Power MOSFET

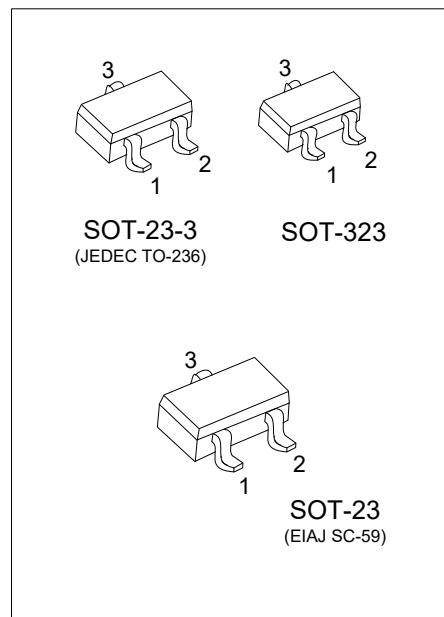
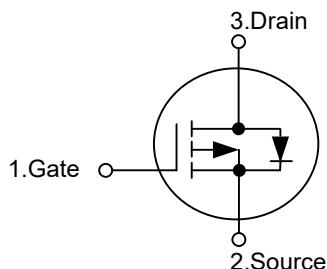
-1.2A, -30V P-CHANNEL ENHANCEMENT MODE POWER MOSFET

■ DESCRIPTION

The UTC **UT7401** is P-channel enhancement mode power MOSFET, designed in serried ranks. With fast switching speed, low on-resistance, favorable stabilization.

Used in commercial and industrial surface mount applications and suited for low voltage applications such as DC/DC converters.

■ SYMBOL



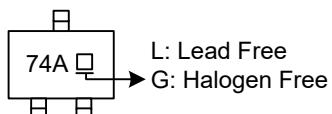
■ ORDERING INFORMATION

Ordering Number		Package	Pin Assignment			Packing
Lead Free	Halogen Free		1	2	3	
UT7401L-AE2-R	UT7401G-AE2-R	SOT-23-3	G	S	D	Tape Reel
UT7401L-AE3-R	UT7401G-AE3-R	SOT-23	G	S	D	Tape Reel
UT7401L-AL3-R	UT7401G-AL3-R	SOT-323	G	S	D	Tape Reel

Note: Pin Assignment: S: Source G: Gate D: Drain

UT7401G-AE2-R	(1)Packing Type (2)Package Type (3)Green Package	(1) R: Tape Reel (2) AE2: SOT-23-3, AE3: SOT-23, AL3: SOT-323 (3) G: Halogen Free and Lead Free, L: Lead Free
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■ MARKING



■ ABSOLUTE MAXIMUM RATINGS ($T_A=25^\circ\text{C}$, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V_{DSS}	-30	V
Gate-Source Voltage		V_{GSS}	± 12	V
Continuous Drain Current (Note 2)	$T_A=25^\circ\text{C}$	I_D	-1.2	A
	$T_A=70^\circ\text{C}$		-1.0	A
Pulsed Drain Current (Note 3)		I_{DM}	-10	A
Avalanche Energy	Single Pulsed (Note 4)	E_{AS}	42	mJ
Power Dissipation (Note 2)	$T_A=25^\circ\text{C}$	P_D	350	mW
	$T_A=70^\circ\text{C}$		220	mW
Junction Temperature		T_J	+150	$^\circ\text{C}$
Storage Temperature		T_{STG}	-55 ~ +150	$^\circ\text{C}$

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. Repetitive Rating: Pulse width limited by maximum junction temperature.

3. Pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.

4. $L=100\text{mH}$, $I_{AS} = -0.9\text{A}$, $V_{DD} = -25\text{V}$, $R_G = 25 \Omega$, Starting $T_J = 25^\circ\text{C}$.

■ THERMAL DATA

PARAMETER	SYMBOL	RATINGS	UNIT
Junction to Ambient	θ_{JA}	357	$^\circ\text{C/W}$

Note: Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

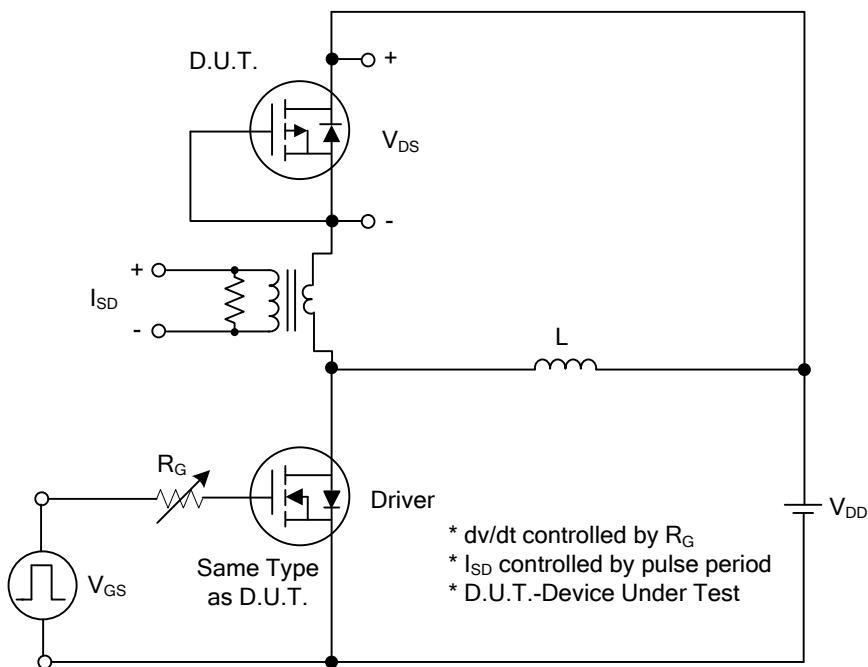
■ ELECTRICAL CHARACTERISTICS ($T_J=25^\circ\text{C}$, unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0\text{V}$, $I_D=-250\mu\text{A}$	-30			V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=-24\text{V}$, $V_{GS}=0\text{V}$			-1	μA
Gate-Source Leakage Current	I_{GSS}	$V_{DS}=0\text{V}$, $V_{GS}=\pm 12\text{V}$			± 100	nA
ON CHARACTERISTICS						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}$, $I_D=-250\mu\text{A}$	-0.6	-0.8	-1.4	V
Drain-Source On-State Resistance (Note 1)	$R_{DS(ON)}$	$V_{GS}=-10\text{V}$, $I_D=-1.2\text{A}$		122	150	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}$, $I_D=-1.2\text{A}$		147	200	$\text{m}\Omega$
		$V_{GS}=-2.5\text{V}$, $I_D=-1.0\text{A}$		207	280	$\text{m}\Omega$
DYNAMIC CHARACTERISTICS						
Input Capacitance	C_{ISS}	$V_{GS}=0\text{V}$, $V_{DS}=-15\text{V}$, $f=1\text{MHz}$		260		pF
Output Capacitance	C_{OSS}			40		pF
Reverse Transfer Capacitance	C_{RSS}			27		pF
SWITCHING CHARACTERISTICS						
Total Gate Charge (Note 1)	Q_G	$V_{DS}=-15\text{V}$, $V_{GS}=-4.5\text{V}$, $I_D=-1.0\text{A}$		2.4		nC
Gate-Source Charge	Q_{GS}			0.52		nC
Gate-Drain Charge	Q_{GD}			0.45		nC
Turn-ON Delay Time (Note 1)	$t_{D(ON)}$	$V_{DS}=-15\text{V}$, $V_{GS}=-10\text{V}$, $R_G=3\Omega$, $I_D=-1.0\text{A}$		2		ns
Turn-ON Rise Time	t_R			16		ns
Turn-OFF Delay Time	$t_{D(OFF)}$			14		ns
Turn-OFF Fall Time	t_F			19		ns
SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS						
Maximum Continuous Drain-Source Diode Forward Current	I_S				-1.2	A
Drain-Source Diode Forward Voltage (Note 2)	V_{SD}	$V_{GS}=0\text{V}$, $I_S=-1.0\text{A}$		-0.85	-1.2	V

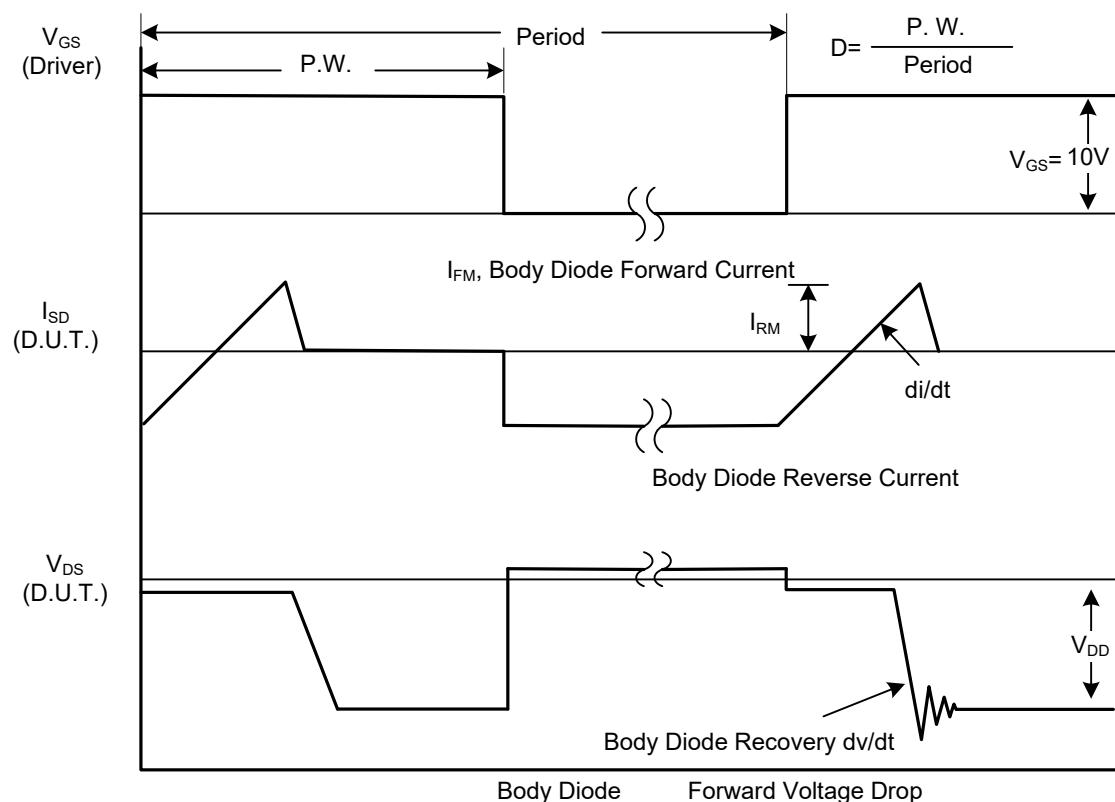
Notes: 1. Pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.

2. Surface mounted on 1 in² copper pad of FR4 board.

■ TEST CIRCUITS AND WAVEFORMS

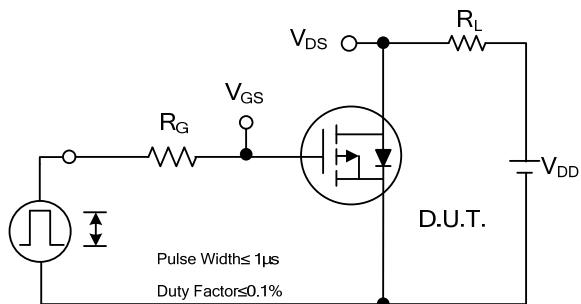


Peak Diode Recovery dv/dt Test Circuit

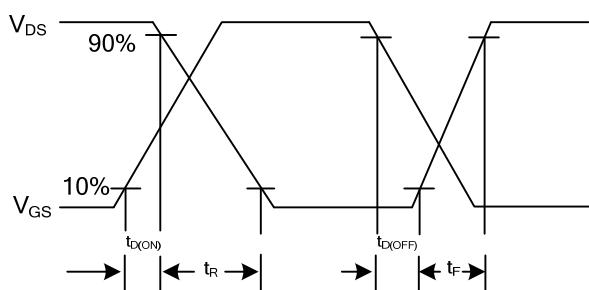


Peak Diode Recovery dv/dt Waveforms

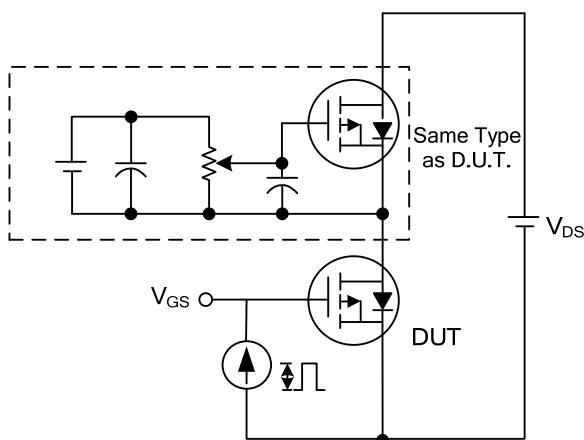
■ TEST CIRCUITS AND WAVEFORMS



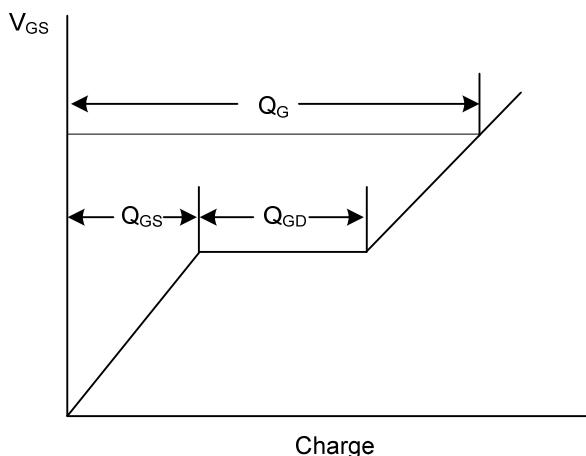
Switching Test Circuit



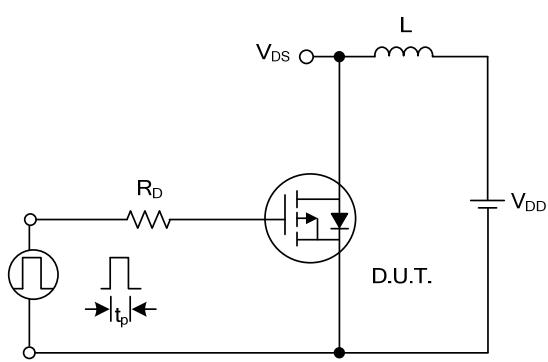
Switching Waveforms



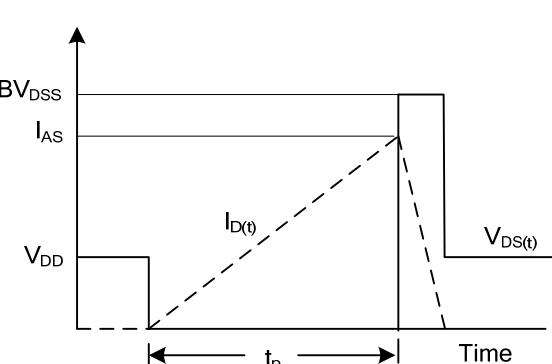
Gate Charge Test Circuit



Gate Charge Waveform

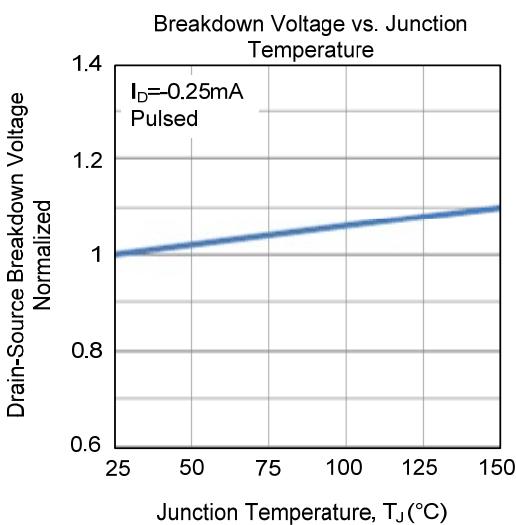
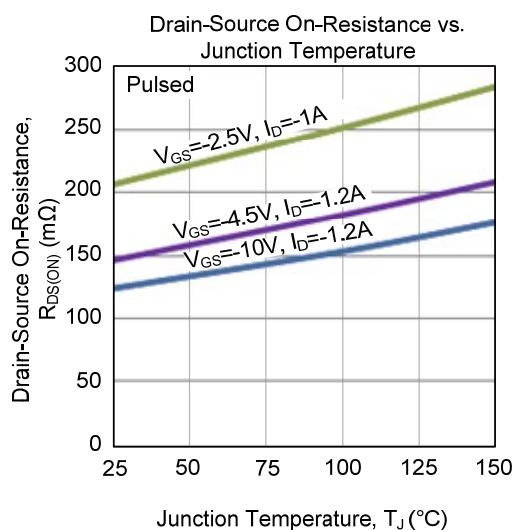
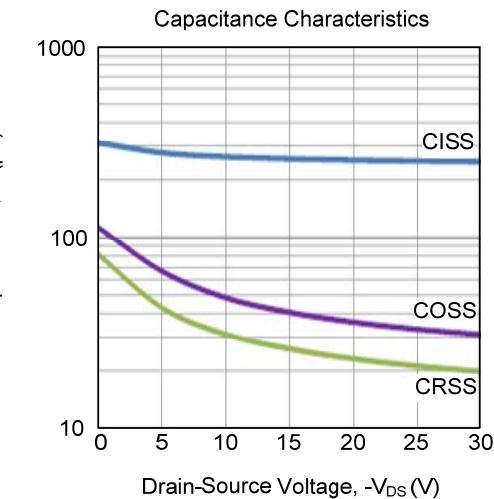
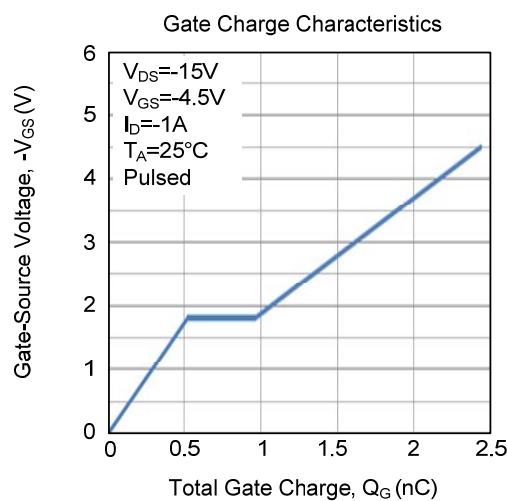
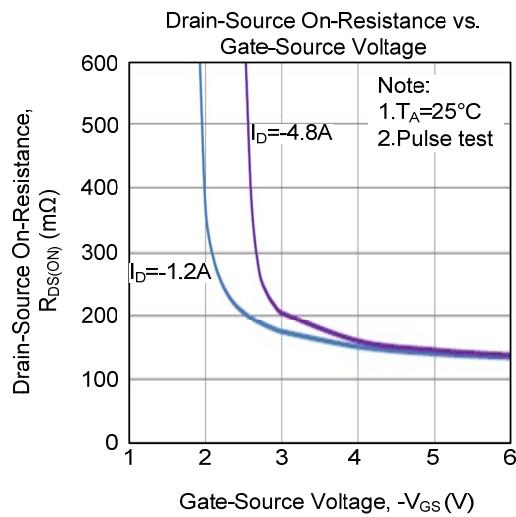
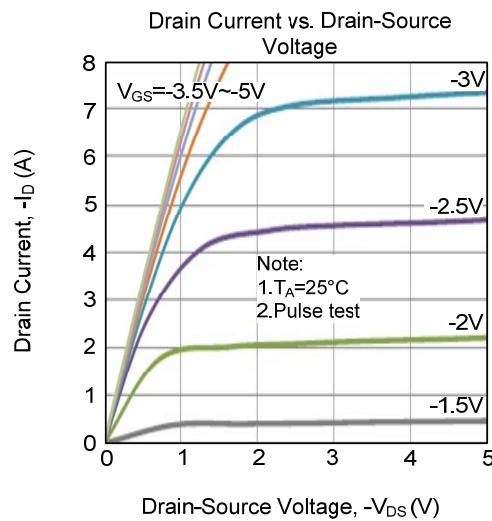


Unclamped Inductive Switching Test Circuit

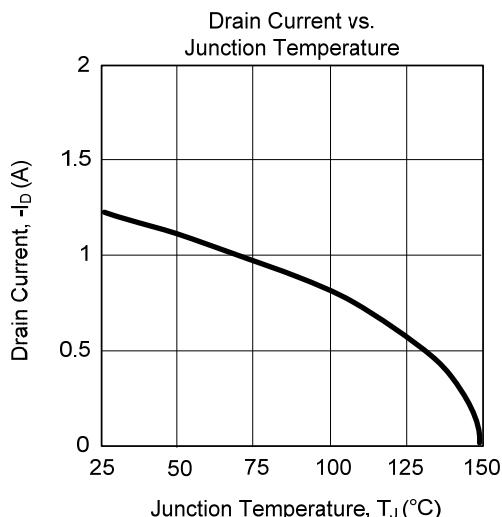
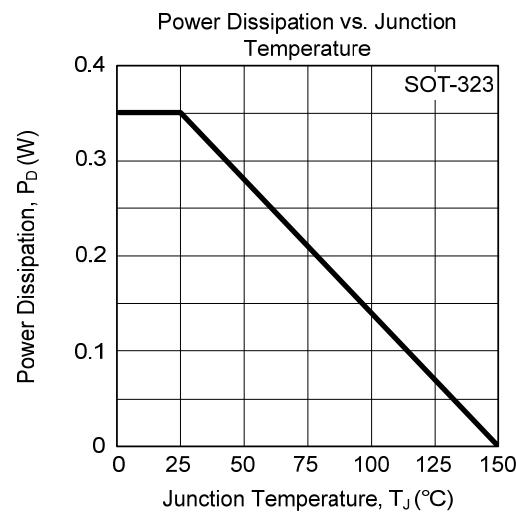
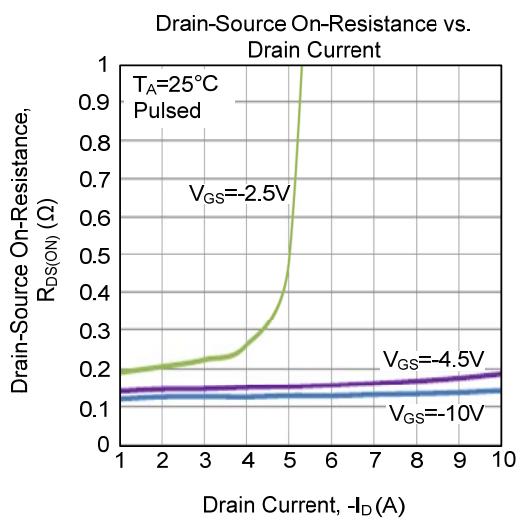
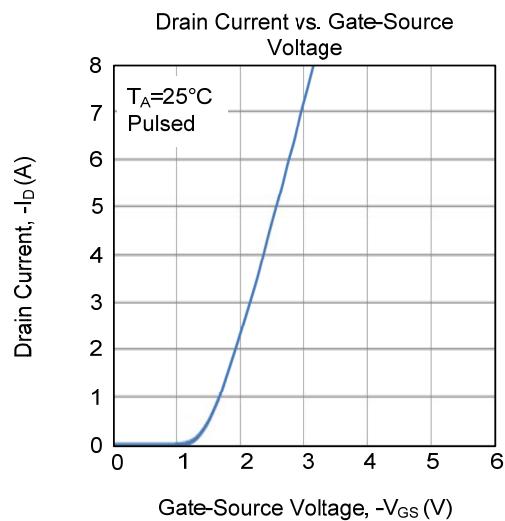
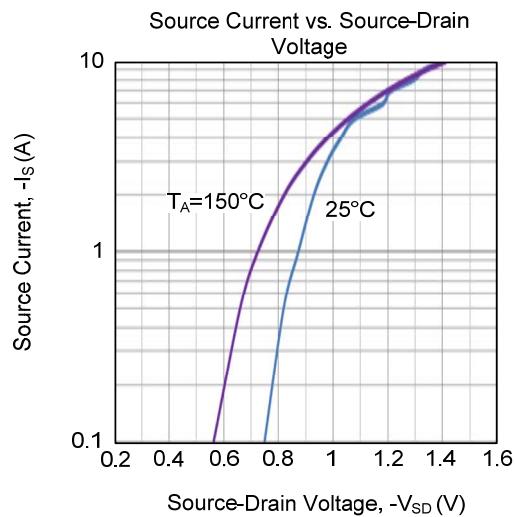
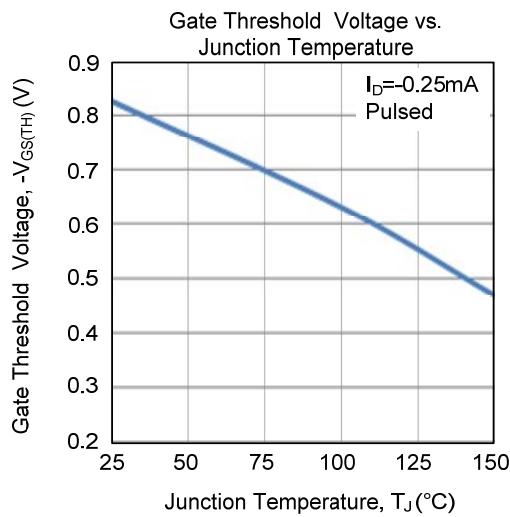


Unclamped Inductive Switching Waveforms

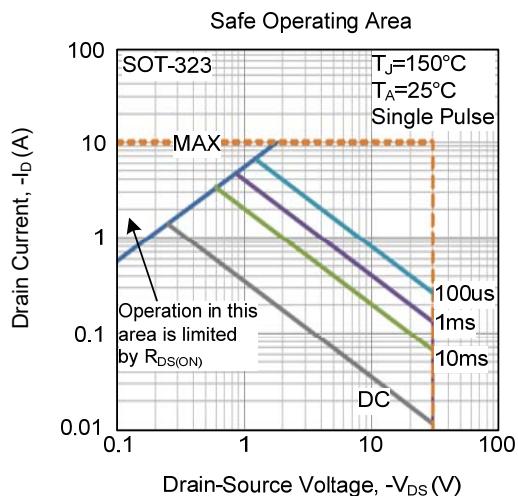
■ TYPICAL CHARACTERISTICS



■ TYPICAL CHARACTERISTICS (Cont.)



- TYPICAL CHARACTERISTICS (Cont.)



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